

IGBT3 Chip Medium Power

Features:

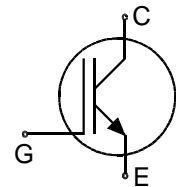
- 650V Trench & Field Stop technology
- high short circuit capability, self limiting short circuit current
- positive temperature coefficient
- easy paralleling
- Qualified according to JEDEC for target applications

Recommended for:

- power modules

Applications:

- drives



Chip Type	V _{CE}	I _{CN}	Die Size	Package
IGC54T65T8RM	650V	100A	5.97 x 8.97 mm ²	sawn on foil

Mechanical Parameters

Die size	5.97 x 8.97		mm ²	
Emitter pad size (incl. gate pad)	See chip drawing			
Gate pad size	1.615 x 0.817			
Area total	53.6		µm	
Thickness	80			
Wafer size	200			
Max.possible chips per wafer	486		mm	
Passivation frontside	Photoimide			
Pad metal	3200 nm AlSiCu			
Backside metal	Ni Ag –system		mm	
Die bond	Electrically conductive epoxy glue and soft solder			
Wire bond	Al, <500µm			
Reject ink dot size	Ø 0.65mm ; max 1.2mm		mm	
Storage environment	for original and sealed MBB bags	Ambient atmosphere air, Temperature 17°C – 25°C, < 6 month		
	for open MBB bags	Acc. to IEC62258-3: Atmosphere >99% Nitrogen or inert gas, Humidity <25%RH, Temperature 17°C – 25°C, < 6 month		



IGC54T65T8RM

Maximum Ratings

Parameter	Symbol	Value	Unit
Collector-Emitter voltage, $T_{vj}=25\text{ °C}$	V_{CE}	650	V
DC collector current, limited by $T_{vj\text{ max}}$	I_C	1)	A
Pulsed collector current, t_p limited by $T_{vj\text{ max}}$ 2)	$I_{C,puls}$	300	A
Gate emitter voltage	V_{GE}	± 20	V
Operating junction temperature	T_{vj}	-40 ... +175	°C
Short circuit data 2)3) $V_{GE} = 15V, V_{CC} = 360V, T_{vj} = 150\text{ °C}$	t_{SC}	10	μs

1) depending on thermal properties of assembly

2) not subject to production test - verified by design/characterization

3) allowed number of short circuits: <1000; time between short circuits: >1s.

Static Characteristics (tested on wafer), $T_{vj}=25\text{ °C}$

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-Emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE}=0V, I_C=4\text{ mA}$	650			V
Collector-Emitter saturation voltage	V_{CEsat}	$V_{GE}=15V, I_C=90A$	1.08	1.55	1.82	
Gate-Emitter threshold voltage	$V_{GE(th)}$	$I_C=1.6mA, V_{GE}=V_{CE}$	5.1	5.8	6.4	
Zero gate voltage collector current	I_{CES}	$V_{CE}=650V, V_{GE}=0V$			0.54	μA
Gate-Emitter leakage current	I_{GES}	$V_{CE}=0V, V_{GE}=20V$			600	nA
Integrated gate resistor	r_G			2		Ω

Electrical Characteristics (not subject to production test - verified by design / characterization)

Parameter	Symbol	Conditions	Value			Unit
			min.	typ.	max.	
Collector-Emitter saturation voltage	V_{CEsat}	$V_{GE}=15V, I_C=100A$		1.55	1.95	V
			$T_{vj}=25\text{ °C}$		1.75	
Input capacitance	C_{ies}	$V_{CE}=25V,$ $V_{GE}=0V, f=1MHz$ $T_{vj}=25\text{ °C}$		6160		pF
Reverse transfer capacitance	C_{res}			183		